

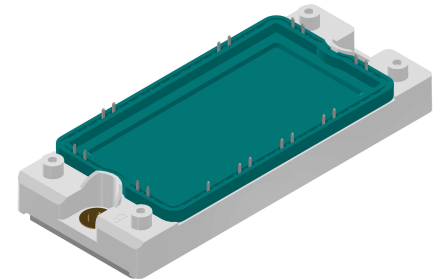
# Standard Rectifier Module

3~ Rectifier	Brake Chopper
$V_{RRM} = 1600 \text{ V}$	$V_{CES} = 1200 \text{ V}$
$I_{DAV} = 120 \text{ A}$	$I_{C25} = 120 \text{ A}$
$I_{FSM} = 700 \text{ A}$	$V_{CE(sat)} = 1.8 \text{ V}$

## 3~ Rectifier Bridge + Brake Unit + NTC

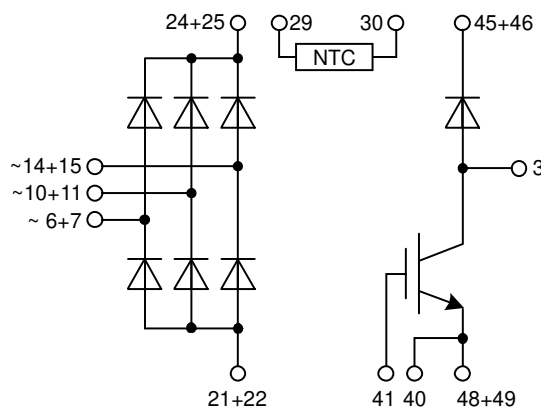
Part number

**VUB116-16NOXT**



Backside: isolated

 E72873



### Features / Advantages:

- Package with DCB ceramic
- Improved temperature and power cycling
- Planar passivated chips
- Very low forward voltage drop
- Very low leakage current
- NTC

### Applications:

- 3~ Rectifier with brake unit for drive inverters

### Package: E2-Pack

- Isolation Voltage: 3600 V~
- Industry standard outline
- RoHS compliant
- Soldering pins for PCB mounting
- Height: 17 mm
- Base plate: Copper internally DCB isolated
- Advanced power cycling
- Phase Change Material available

### Disclaimer Notice

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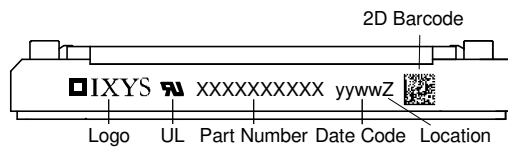
Rectifier				Ratings			
Symbol	Definition	Conditions		min.	typ.	max.	Unit
$V_{RSM}$	max. non-repetitive reverse blocking voltage					1700	V
$V_{RRM}$	max. repetitive reverse blocking voltage					1600	V
$I_R$	reverse current	$V_R = 1600$ V		$T_{VJ} = 25^\circ\text{C}$		100	$\mu\text{A}$
		$V_R = 1600$ V		$T_{VJ} = 150^\circ\text{C}$		1.5	mA
$V_F$	forward voltage drop	$I_F = 40$ A		$T_{VJ} = 25^\circ\text{C}$		1.19	V
		$I_F = 120$ A				1.64	V
		$I_F = 40$ A		$T_{VJ} = 125^\circ\text{C}$		1.12	V
		$I_F = 120$ A				1.70	V
$I_{DAV}$	bridge output current	$T_C = 105^\circ\text{C}$		$T_{VJ} = 150^\circ\text{C}$		120	A
		rectangular	$d = \frac{1}{3}$				
$V_{FO}$	threshold voltage			$T_{VJ} = 150^\circ\text{C}$		0.80	V
$r_F$	slope resistance					7.6	m $\Omega$
$R_{thJC}$	thermal resistance junction to case					0.65	K/W
$R_{thCH}$	thermal resistance case to heatsink				0.1		K/W
$P_{tot}$	total power dissipation			$T_C = 25^\circ\text{C}$		190	W
$I_{FSM}$	max. forward surge current	$t = 10$ ms; (50 Hz), sine		$T_{VJ} = 45^\circ\text{C}$		700	A
		$t = 8,3$ ms; (60 Hz), sine		$V_R = 0$ V		755	A
		$t = 10$ ms; (50 Hz), sine		$T_{VJ} = 150^\circ\text{C}$		595	A
		$t = 8,3$ ms; (60 Hz), sine		$V_R = 0$ V		645	A
$I^2t$	value for fusing	$t = 10$ ms; (50 Hz), sine		$T_{VJ} = 45^\circ\text{C}$		2.45	kA <sup>2</sup> s
		$t = 8,3$ ms; (60 Hz), sine		$V_R = 0$ V		2.37	kA <sup>2</sup> s
		$t = 10$ ms; (50 Hz), sine		$T_{VJ} = 150^\circ\text{C}$		1.77	kA <sup>2</sup> s
		$t = 8,3$ ms; (60 Hz), sine		$V_R = 0$ V		1.73	kA <sup>2</sup> s
$C_J$	junction capacitance	$V_R = 400$ V; $f = 1$ MHz		$T_{VJ} = 25^\circ\text{C}$		27	pF



Brake IGBT				Ratings			
Symbol	Definition	Conditions	min.	typ.	max.	Unit	
$V_{CES}$	collector emitter voltage				1200	V	
$V_{GES}$	max. DC gate voltage				±20	V	
$V_{GEM}$	max. transient gate emitter voltage				±30	V	
$I_{C25}$	collector current				120	A	
$I_{C80}$					84	A	
$P_{tot}$	total power dissipation				390	W	
$V_{CE(sat)}$	collector emitter saturation voltage	$I_C = 75 \text{ A}; V_{GE} = 15 \text{ V}$		1.8	2.1	V	
				2.1		V	
$V_{GE(th)}$	gate emitter threshold voltage	$I_C = 3 \text{ mA}; V_{GE} = V_{CE}$	5.5	6.0	6.5	V	
$I_{CES}$	collector emitter leakage current	$V_{CE} = V_{CES}; V_{GE} = 0 \text{ V}$			0.2	mA	
				0.6		mA	
$I_{GES}$	gate emitter leakage current	$V_{GE} = \pm 20 \text{ V}$			500	nA	
$Q_{G(on)}$	total gate charge	$V_{CE} = 600 \text{ V}; V_{GE} = 15 \text{ V}; I_C = 75 \text{ A}$		230		nC	
$t_{d(on)}$	turn-on delay time	inductive load $V_{CE} = 600 \text{ V}; I_C = 75 \text{ A}$ $V_{GE} = \pm 15 \text{ V}; R_G = 10 \Omega$		70		ns	
$t_r$	current rise time			40		ns	
$t_{d(off)}$	turn-off delay time			250		ns	
$t_f$	current fall time			100		ns	
$E_{on}$	turn-on energy per pulse			6.8		mJ	
$E_{off}$	turn-off energy per pulse			8.3		mJ	
<b>RBSOA</b>	reverse bias safe operating area	$V_{GE} = \pm 15 \text{ V}; R_G = 10 \Omega$					
$I_{CM}$		$V_{CEK} = 1200 \text{ V}$			225	A	
<b>SCSOA</b>	short circuit safe operating area	$V_{CEK} = 1200 \text{ V}$					
$t_{SC}$	short circuit duration	$V_{CE} = 900 \text{ V}; V_{GE} = \pm 15$			10	µs	
$I_{SC}$	short circuit current	$R_G = 10 \Omega$ ; non-repetitive		300		A	
$R_{thJC}$	thermal resistance junction to case				0.32	K/W	
$R_{thCH}$	thermal resistance case to heatsink			0.15		K/W	
<b>Brake Diode</b>							
$V_{RRM}$	max. repetitive reverse voltage				1200	V	
$I_{F25}$	forward current				48	A	
$I_{F80}$					32	A	
$V_F$	forward voltage	$I_F = 30 \text{ A}$			2.75	V	
				1.99		V	
$I_R$	reverse current	$V_R = V_{RRM}$			0.25	mA	
					1	mA	
$Q_{rr}$	reverse recovery charge	$V_R = 600 \text{ V}$ $-di_f/dt = 400 \text{ A}/\mu\text{s}$ $I_F = 30 \text{ A}; V_{GE} = 0 \text{ V}$		1.8		µC	
$I_{RM}$	max. reverse recovery current			23		A	
$t_{rr}$	reverse recovery time			150		ns	
$R_{thJC}$	thermal resistance junction to case				0.9	K/W	
$R_{thCH}$	thermal resistance case to heatsink			0.3		K/W	



Package E2-Pack			Ratings			
Symbol	Definition	Conditions	min.	typ.	max.	Unit
$I_{RMS}$	RMS current	per terminal			50	A
$T_{VJ}$	virtual junction temperature		-40		150	°C
$T_{op}$	operation temperature		-40		125	°C
$T_{stg}$	storage temperature		-40		125	°C
<b>Weight</b>				176		g
$M_D$	mounting torque		3		6	Nm
$d_{Spp/App}$	creepage distance on surface / striking distance through air	terminal to terminal	6.0			mm
$d_{Spb/Apb}$		terminal to backside	12.0			mm
$V_{ISOL}$	isolation voltage	t = 1 second t = 1 minute	3600 3000			V V
		50/60 Hz, RMS; $I_{ISOL} \leq 1$ mA				



Ordering	Ordering Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	VUB116-16NOXT	VUB116-16NOXT	Box	6	510755

**Temperature Sensor NTC**

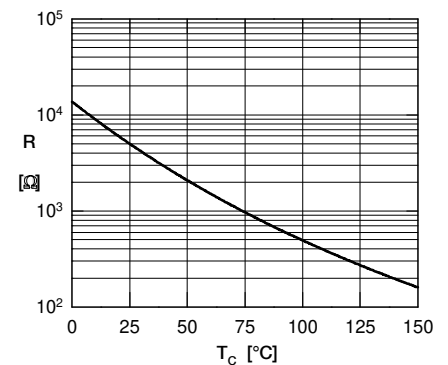
Symbol	Definition	Conditions	min.	typ.	max.	Unit
$R_{25}$	resistance	$T_{VJ} = 25^\circ$	4.75	5	5.25	k $\Omega$
$B_{25/50}$	temperature coefficient			3375		K

**Equivalent Circuits for Simulation**

\* on die level

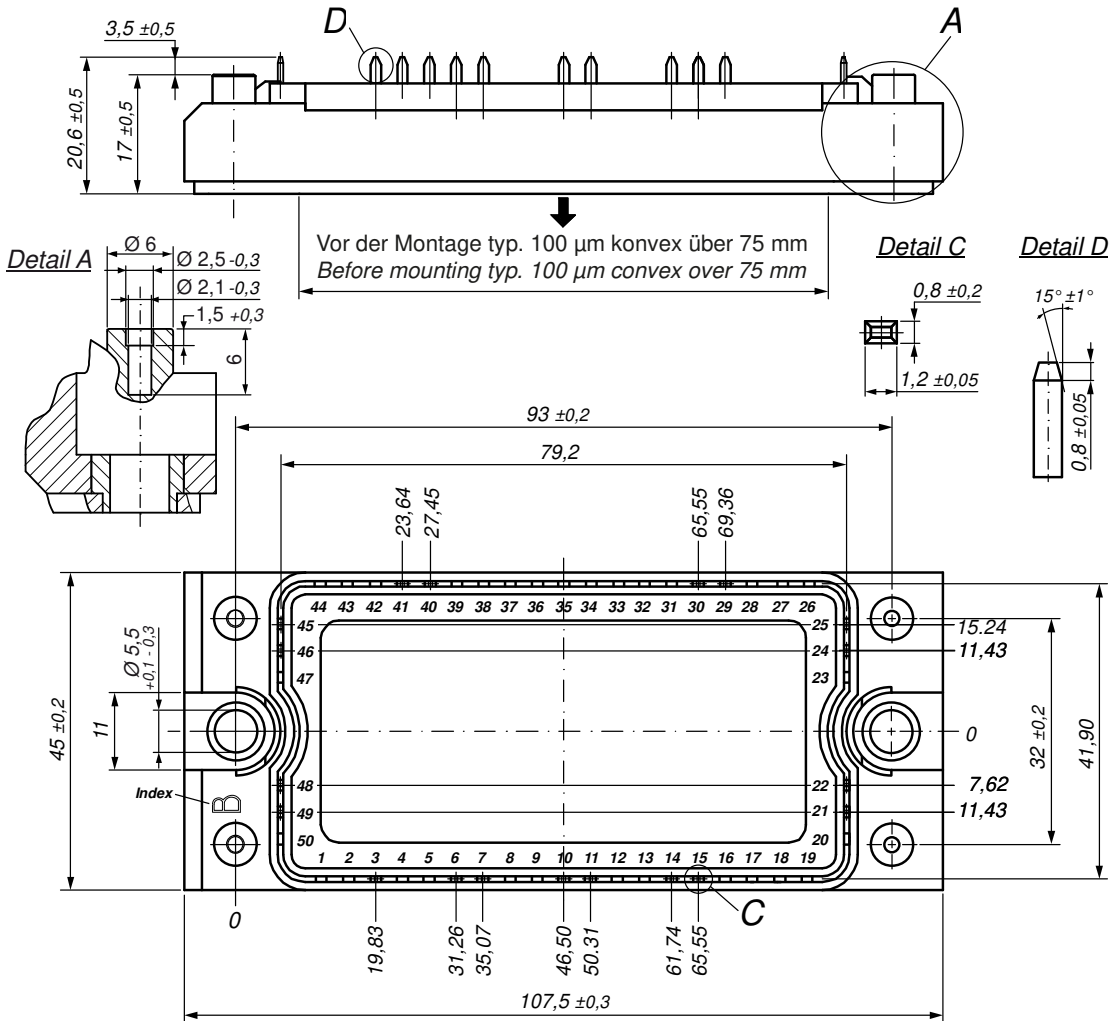
$T_{VJ} = 150^\circ\text{C}$

	Rectifier	Brake IGBT	Brake Diode	
$V_0$ max	0.8	1.1	1.31	V
$R_0$ max	4.5	17.9	8	m $\Omega$





**Outlines E2-Pack**

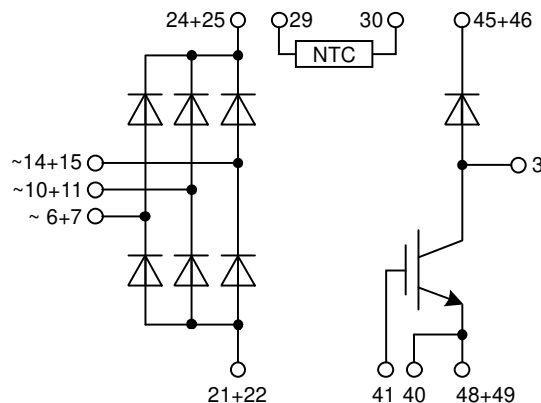


**Bemerkung / Note:**

- Nichttolerierete Maße nach / Measure without tolerances according DIN ISO 2768-T1-m
- PCB-Lochmuster / PCB hole pattern: **see pin position**
- Toleranz Pin-Position und PCB-Lochmuster / Tolerance of pin position and PCB hole pattern:  $\oplus 0,1$
- Montageanleitung / Mounting instruction: [www.ixys.com](http://www.ixys.com) **Application note IXAN0024**

**Detail A:** PCB-Montage / Mounting on PCB <sup>L</sup>

- Empfohlene, selbstschneidende Schraube / Recommended, self-tapping screw: **EJOT PT®** (Größe / size: **K25**) <sup>L</sup>
- Max. Schraubenlänge / Max. screw length: **PCB-Dicke / thickness + 6 mm** (max. Lochtiefe / hole depth) <sup>L</sup>
- Empfohlenes Drehmoment / Recommended mounting torque: **1.5 Nm**



**Rectifier**

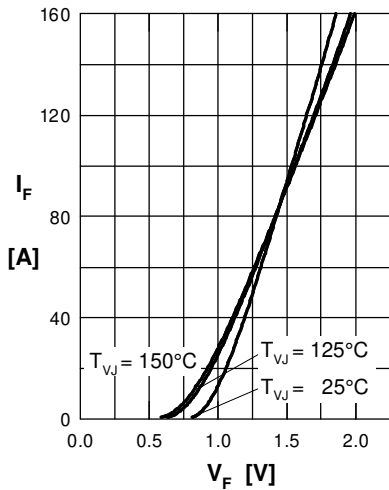


Fig. 1 Forward current versus voltage drop per diode

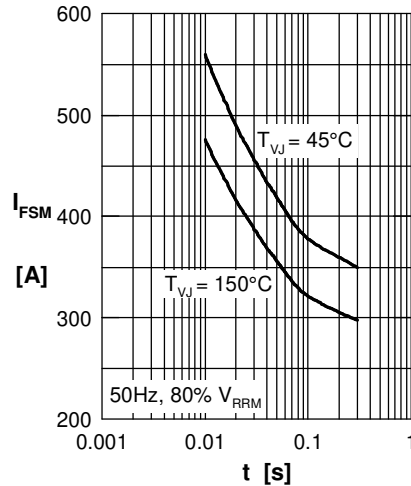


Fig. 2 Surge overload current vs. time per diode

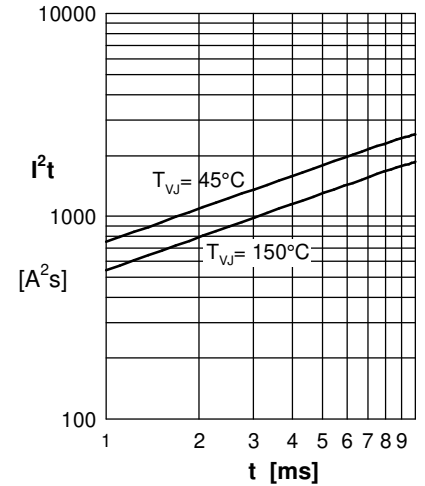


Fig. 3  $I^2t$  versus time per diode

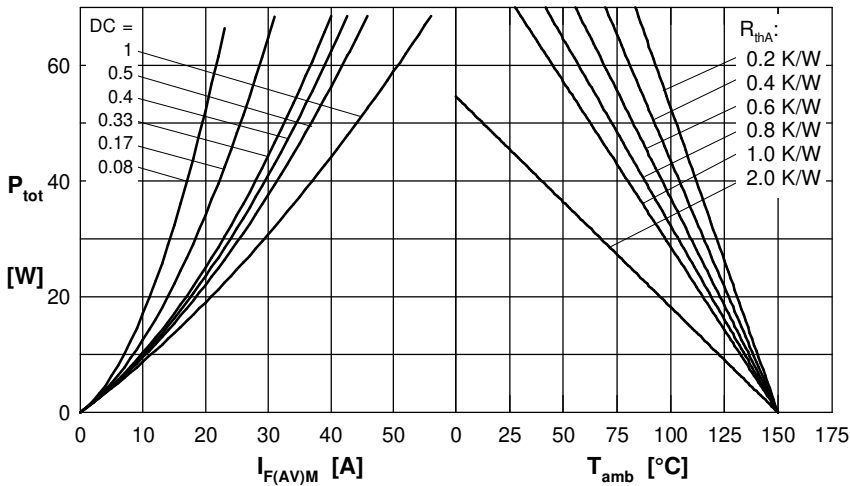


Fig. 4 Power dissipation vs. forward current and ambient temperature per diode

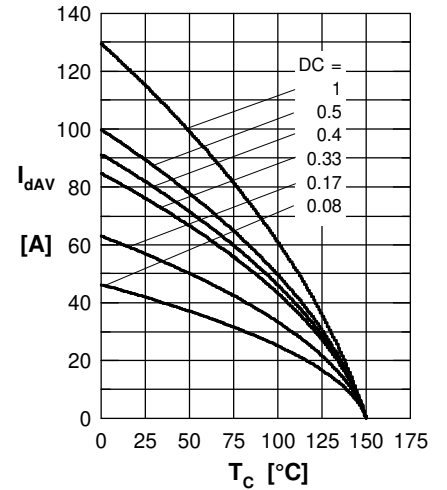


Fig. 5 Max. forward current vs. case temperature per diode

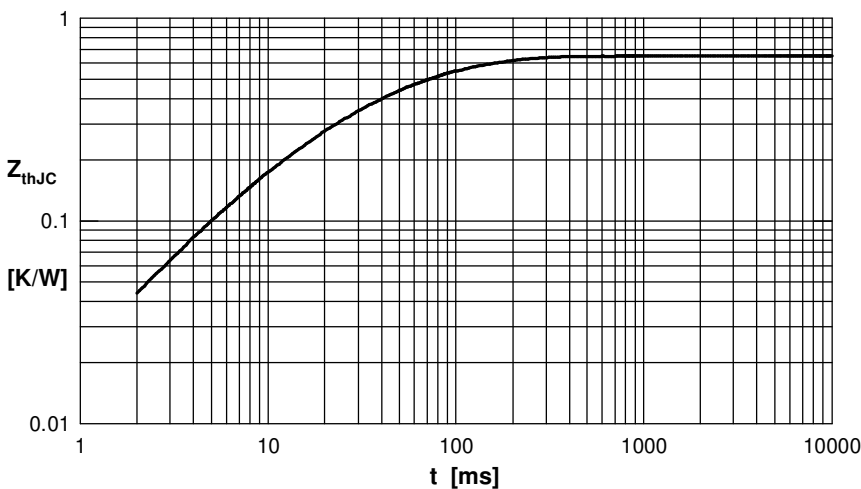


Fig. 6 Transient thermal impedance junction to case vs. time per diode

$R_i$	$t_i$
0.085	0.012
0.041	0.007
0.309	0.036
0.215	0.102



**Brake IGBT**

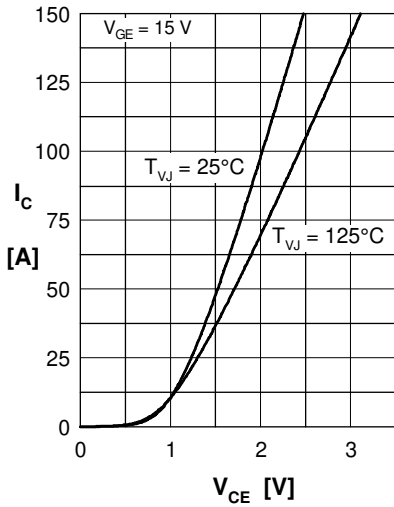


Fig. 1 Typ. output characteristics

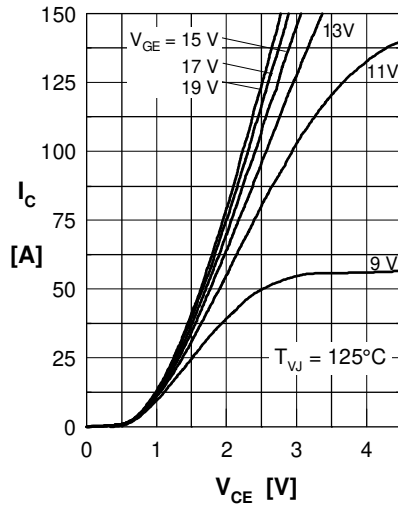


Fig. 2 Typ. output characteristics

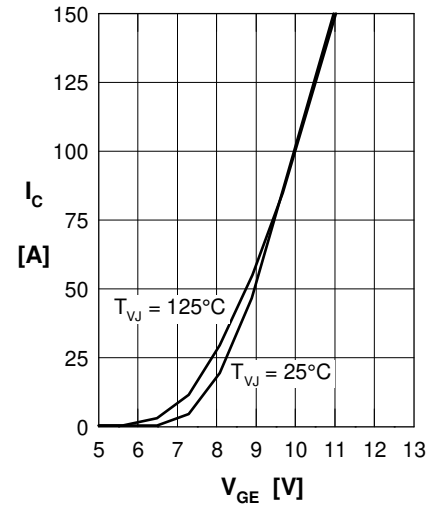


Fig. 3 Typ. transfer characteristics

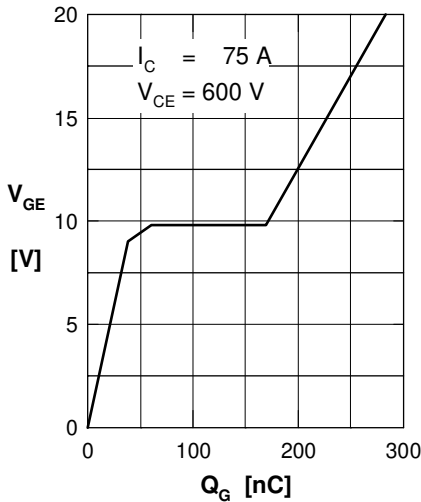


Fig. 4 Typ. turn-on gate charge

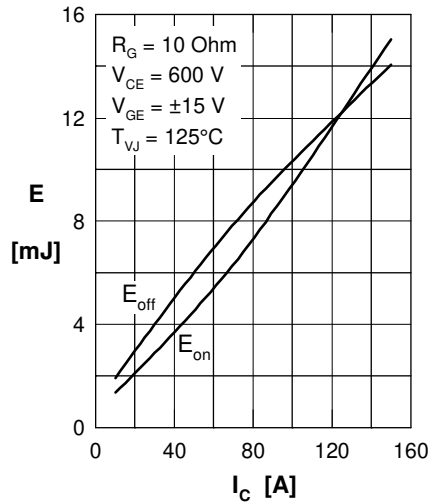


Fig. 5 Typ. switching energy versus collector current

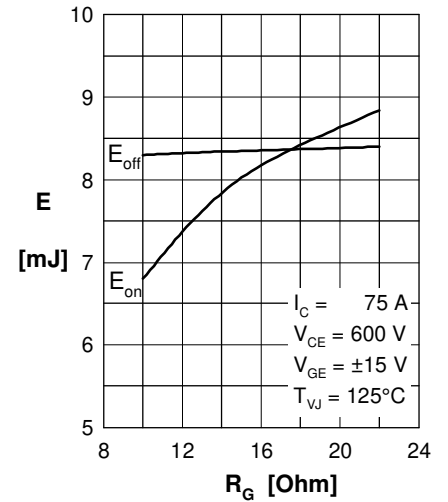


Fig. 6 Typ. switching energy versus gate resistance

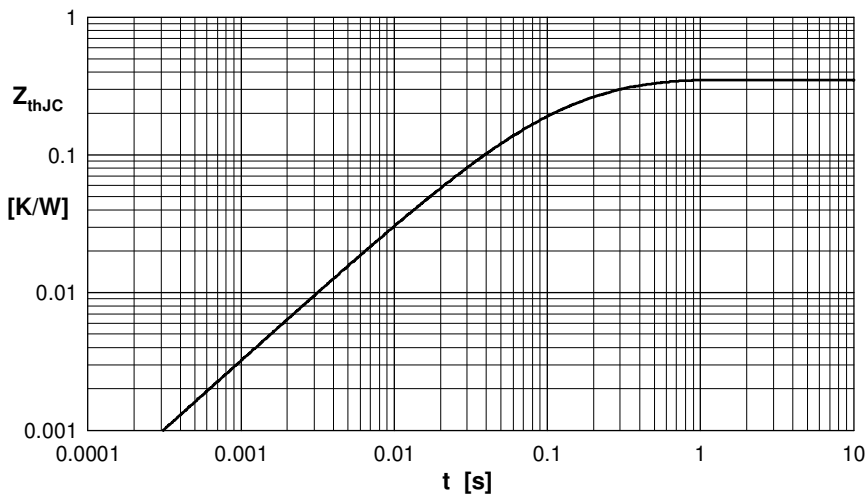


Fig. 7 Typ. transient thermal impedance junction to case

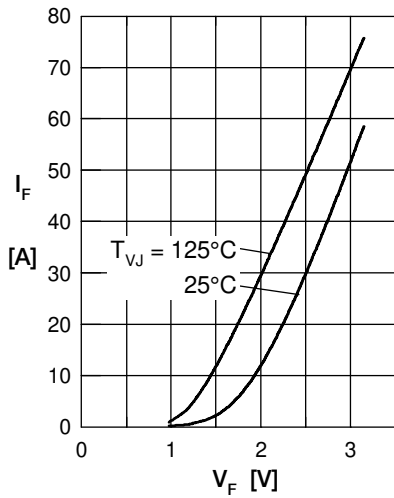
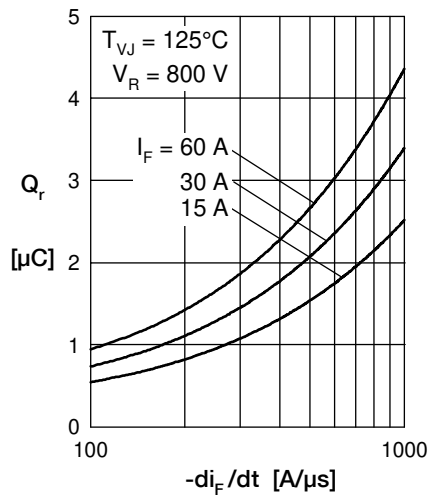
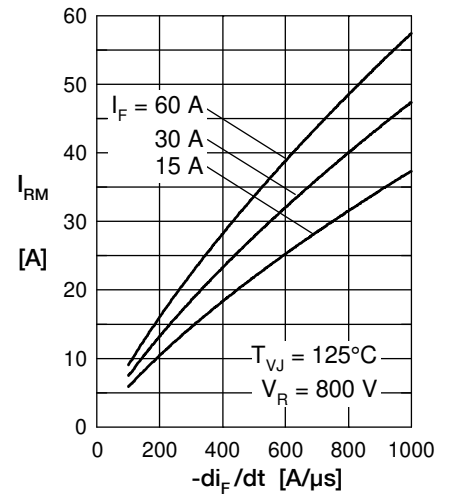
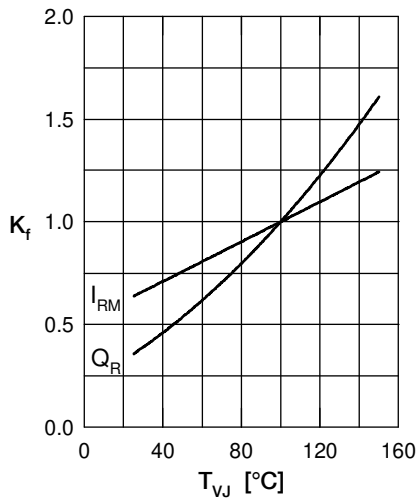
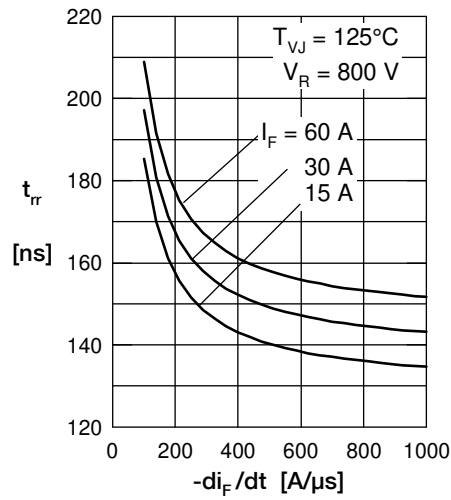
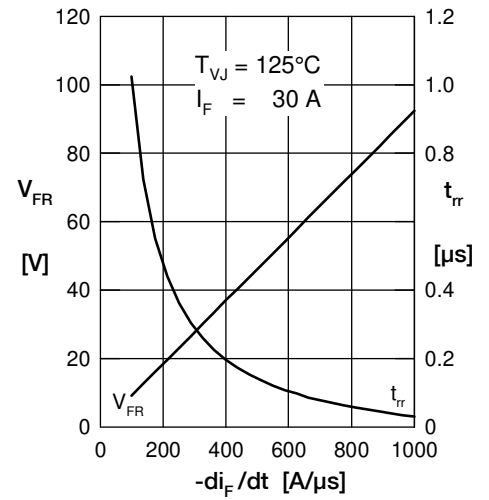
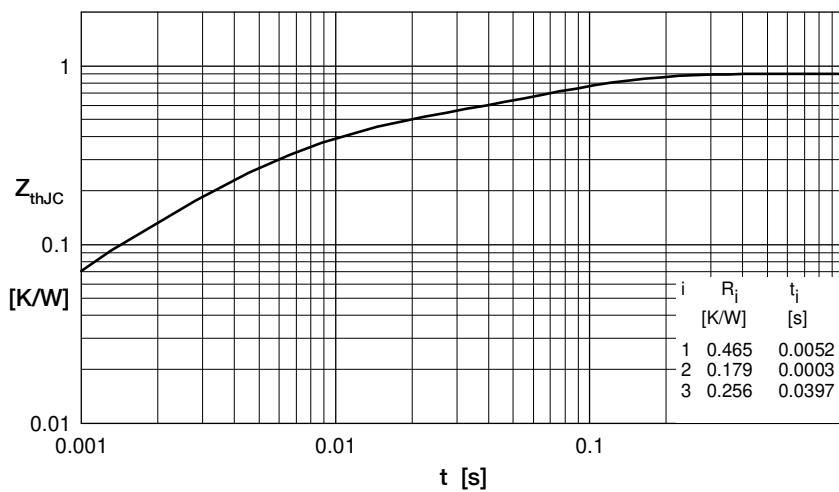
**Brake Diode**

 Fig. 1 Forward current  $I_F$  vs.  $V_F$ 

 Fig. 2 Typ. reverse recovery charge  $Q_r$  versus  $-di_F/dt$ 

 Fig. 3 Typ. peak reverse current  $I_{RM}$  versus  $-di_F/dt$ 

 Fig. 4 Dynamic parameters  $Q_r$ ,  $I_{RM}$  versus  $T_{VJ}$ 

 Fig. 5 Typ. recovery time  $t_{rr}$  versus  $-di_F/dt$ 

 Fig. 6 Typ. peak forward voltage  $V_{FR}$  and  $t_{rr}$  versus  $di_F/dt$ 


Fig. 7 Transient thermal impedance junction to case